



3.3V CMOS 12-BIT TO 24-BIT MULTIPLEXED BUS EXCHANGER WITH 3-STATE OUTPUTS AND BUS-HOLD

IDT74ALVCH16271

FEATURES:

- 0.5 MICRON CMOS Technology
- Typical $t_{sk(0)}$ (Output Skew) < 250ps
- ESD > 2000V per MIL-STD-883, Method 3015;
> 200V using machine model (C = 200pF, R = 0)
- 0.635mm pitch SSOP, 0.50mm pitch TSSOP,
and 0.40mm pitch TVSOP packages
- Extended commercial range of -40°C to $+85^{\circ}\text{C}$
- $V_{CC} = 3.3\text{V} \pm 0.3\text{V}$, Normal Range
- $V_{CC} = 2.7\text{V}$ to 3.6V , Extended Range
- $V_{CC} = 2.5\text{V} \pm 0.2\text{V}$
- CMOS power levels (0.4μW typ. static)
- Rail-to-Rail output swing for increased noise margin

Drive Features for ALVCH16271:

- High Output Drivers: $\pm 24\text{mA}$
- Suitable for heavy loads

APPLICATIONS:

- 3.3V High Speed Systems
- 3.3V and lower voltage computing systems

DESCRIPTION:

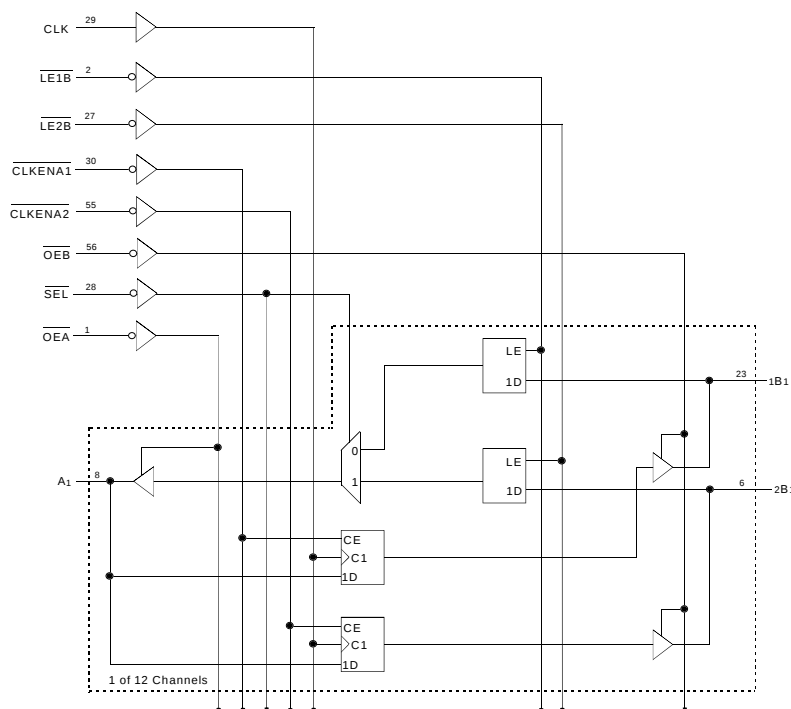
The ALVCH16271 is intended for applications in which two separate data paths must be multiplexed onto, or demultiplexed from, a single data path. This device is particularly suitable as an interface between conventional DRAMs and high-speed microprocessors.

A data is stored in the internal A-to-B registers on the low-to-high transition of the clock (CLK) input, provided that the clock-enable (CLKENA) inputs are low. Proper control of these inputs allows two sequential 12-bit words to be presented as a 24-bit word on the B port. Transparent latches in the B-to-A path allow asynchronous operation to maximize memory access throughput. These latches transfer data when the latch-enable ($\overline{\text{LE}}$) inputs are low. The select (SEL) line selects 1B or 2B data for the A inputs. Data flow is controlled by the active-low output enables ($\overline{\text{OEA}}$, $\overline{\text{OEB}}$).

The ALVCH16271 has been designed with a $\pm 24\text{mA}$ output driver. This driver is capable of driving a moderate to heavy load while maintaining speed performance.

The ALVCH16271 has "bus-hold" which retains the inputs' last state whenever the input goes to a high impedance. This prevents floating inputs and eliminates the need for pull-up/down resistors.

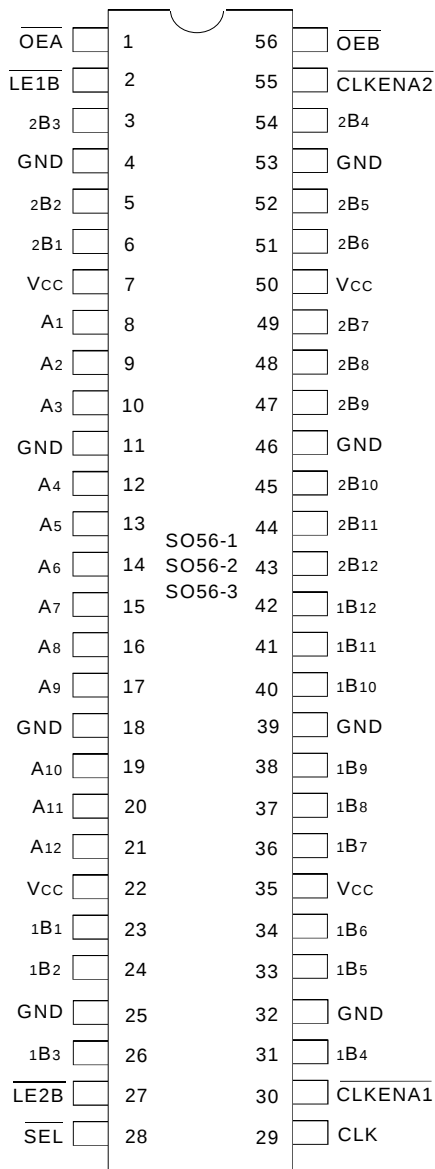
Functional Block Diagram



EXTENDED COMMERCIAL TEMPERATURE RANGE

MARCH 1999

PIN CONFIGURATION



SSOP/
TSSOP/TVSOP
TOP VIEW

FUNCTION TABLES⁽¹⁾

OUTPUT ENABLE

Inputs		Outputs	
$\overline{\text{OEA}}$	$\overline{\text{OEB}}$	Ax	1Bx, 2Bx
H	H	Z	Z
H	L	Z	Active
L	H	Active	Z
L	L	Active	Active

A-TO-B STORAGE ($\overline{\text{OEB}} = \text{L}$)

Inputs			Outputs		
$\overline{\text{CLKENA1}}$	$\overline{\text{CLKENA2}}$	CLK	Ax	1Bx	2Bx
H	H	X	X	1Bo ⁽²⁾	2Bo ⁽²⁾
L	X	↑	L	L	X
L	X	↑	H	H	X
X	L	↑	L	X	L
X	L	↑	H	X	H

B-TO-A STORAGE ($\overline{\text{OEA}} = \text{L}$)

Inputs				Outputs	
$\overline{\text{LE1B}}$	$\overline{\text{LE2B}}$	$\overline{\text{SEL}}$	1Bx	2Bx	Ax
H	H	X	X	X	Ao ⁽²⁾
H	H	X	X	X	Ao ⁽²⁾
L	X	H	L	X	L
L	X	H	H	X	H
X	L	L	X	L	L
X	L	L	X	H	H

NOTES:

- H = HIGH Voltage Level
L = LOW Voltage Level
X = Don't Care
Z = High-Impedance
↑ = LOW-to-HIGH Transition
- Output level before the indicated steady-state input conditions were established.

PIN DESCRIPTION

Pin Names	I/O	Description
AX(1:12)	I/O	Bidirectional Data Port A. Usually connected to the CPU's Address/Data bus. ⁽¹⁾
1BX(1:12)	I/O	Bidirectional Data Port 1B. Usually connected to the even path or even bank of memory. ⁽¹⁾
2BX(1:12)	I/O	Bidirectional Data Port 2B. Usually connected to the odd path or odd bank of memory. ⁽¹⁾
CLK	I	Clock Input
$\overline{\text{CLKENA1}}$	I	Clock Enable Input for the A-1B Register. If $\overline{\text{CLKENA1}}$ is LOW during the rising edge of CLK, data will be clocked into register A-1B (Active LOW).
$\overline{\text{CLKENA2}}$	I	Clock Enable Input for the A-2B Register. If $\overline{\text{CLKENA2}}$ is LOW during the rising edge of CLK, data will be clocked into register A-2B (Active LOW).
$\overline{\text{LE1B}}$	I	Latch-Enable Input for the 1B-A Latch
$\overline{\text{LE2B}}$	I	Latch-Enable Input for the 2B-A Latch
$\overline{\text{SEL}}$	I	1B or 2B Port Selection. When HIGH, $\overline{\text{SEL}}$ enables data transfer from 1B Port to A Port. When LOW, $\overline{\text{SEL}}$ enables data transfer from 2B Port to A Port (Active LOW).
$\overline{\text{OEA}}$	I	Output Enable for A Port (Active LOW)
$\overline{\text{OEB}}$	I	Output Enable for B Port (Active LOW)

NOTE:

1. These pins have "Bus-Hold." All other pins are standard inputs, outputs, or I/Os.

ABSOLUTE MAXIMUM RATING ⁽¹⁾

Symbol	Description	Max.	Unit
V _{TERM} ⁽²⁾	Terminal Voltage with Respect to GND	– 0.5 to + 4.6	V
V _{TERM} ⁽³⁾	Terminal Voltage with Respect to GND	– 0.5 to V _{CC} + 0.5	V
T _{STG}	Storage Temperature	– 65 to + 150	°C
I _{OUT}	DC Output Current	– 50 to + 50	mA
I _{IK}	Continuous Clamp Current, V _I < 0 or V _I > V _{CC}	± 50	mA
I _{OK}	Continuous Clamp Current, V _O < 0	– 50	mA
I _{CC} I _{SS}	Continuous Current through each V _{CC} or GND	±100	mA

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NOTES:

1. Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.
2. V_{CC} terminals.
3. All terminals except V_{CC}.

CAPACITANCE (T_A = +25°C, f = 1.0MHz)

Symbol	Parameter ⁽¹⁾	Conditions	Typ.	Max.	Unit
C _{IN}	Input Capacitance	V _{IN} = 0V	5	7	pF
C _{OUT}	Output Capacitance	V _{OUT} = 0V	7	9	pF
C _{I/O}	I/O Port Capacitance	V _{IN} = 0V	7	9	pF

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NOTE:

1. As applicable to the device type.

DC ELECTRICAL CHARACTERISTICS OVER OPERATING RANGE

Following Conditions Apply Unless Otherwise Specified:

Operating Condition: TA = – 40°C to +85°C

Symbol	Parameter	Test Conditions		Min.	Typ. ⁽¹⁾	Max.	Unit
VIH	Input HIGH Voltage Level	VCC = 2.3V to 2.7V		1.7	—	—	V
		VCC = 2.7V to 3.6V		2	—	—	
VIL	Input LOW Voltage Level	VCC = 2.3V to 2.7V		—	—	0.7	V
		VCC = 2.7V to 3.6V		—	—	0.8	
IiH	Input HIGH Current	VCC = 3.6V	Vi = VCC	—	—	± 5	μA
IiL	Input LOW Current	VCC = 3.6V	Vi = GND	—	—	± 5	
IoZH IoZL	High Impedance Output Current (3-State Output pins)	VCC = 3.6V	Vo = VCC	—	—	± 10	μA
			Vo = GND	—	—	± 10	μA
Vik	Clamp Diode Voltage	VCC = 2.3V, IIN = – 18mA		—	– 0.7	– 1.2	V
VH	Input Hysteresis	VCC = 3.3V		—	100	—	mV
IcCL IcCH IcCZ	Quiescent Power Supply Current	VCC = 3.6V VIN = GND or VCC		—	0.1	40	μA
ΔIcc	Quiescent Power Supply Current Variation	One input at VCC – 0.6V, other inputs at VCC or GND		—	—	750	μA

NOTE:

- Typical values are at VCC = 3.3V, +25°C ambient.

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BUS-HOLD CHARACTERISTICS

Symbol	Parameter ⁽¹⁾	Test Conditions		Min.	Typ. ⁽²⁾	Max.	Unit
IBHH IBHL	Bus-Hold Input Sustain Current	VCC = 3.0V	Vi = 2.0V	– 75	—	—	μA
			Vi = 0.8V	75	—	—	
IBHH IBHL	Bus-Hold Input Sustain Current	VCC = 2.3V	Vi = 1.7V	– 45	—	—	μA
			Vi = 0.7V	45	—	—	
IBHHO IBHLO	Bus-Hold Input Overdrive Current	VCC = 3.6V	Vi = 0 to 3.6V	—	—	± 500	μA

NOTES:

- Pins with Bus-hold are identified in the pin description.
- Typical values are at VCC = 3.3V, +25°C ambient.

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OUTPUT DRIVE CHARACTERISTICS

Symbol	Parameter	Test Conditions ⁽¹⁾		Min.	Max.	Unit
VOH	Output HIGH Voltage	VCC = 2.3V to 3.6V	IOH = - 0.1mA	VCC - 0.2	—	V
		VCC = 2.3V	IOH = - 6mA	2	—	
		VCC = 2.3V	IOH = - 12mA	1.7	—	
		VCC = 2.7V		2.2	—	
		VCC = 3.0V		2.4	—	
		VCC = 3.0V	IOH = - 24mA	2	—	
VOL	Output LOW Voltage	VCC = 2.3V to 3.6V	IOL = 0.1mA	—	0.2	V
		VCC = 2.3V	IOL = 6mA	—	0.4	
			IOL = 12mA	—	0.7	
		VCC = 2.7V	IOL = 12mA	—	0.4	
		VCC = 3.0V	IOL = 24mA	—	0.55	

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NOTE:

1. VIH and VIL must be within the min. or max. range shown in the DC ELECTRICAL CHARACTERISTICS OVER OPERATING RANGE table for the appropriate VCC range. TA = - 40°C to + 85°C.

OPERATING CHARACTERISTICS, TA = 25°C

Symbol	Parameter	Test Conditions	VCC = 2.5V ± 0.2V	VCC = 3.3V ± 0.3V	Unit
			Typical	Typical	
CPD	Power Dissipation Capacitance Ax to xBx, outputs enabled	CL = 0pF, f = 10Mhz	92	105	pF
CPD	Power Dissipation Capacitance Ax to xBx, outputs disabled		61	76	pF
CPD	Power Dissipation Capacitance xBx to Ax, outputs enabled		39	43	pF
CPD	Power Dissipation Capacitance xBx to Ax, outputs disabled		11	13	pF

SWITCHING CHARACTERISTICS ⁽¹⁾

Symbol	Parameter	V _{CC} = 2.5V ± 0.2V		V _{CC} = 2.7V		V _{CC} = 3.3V ± 0.3V		Unit
		Min.	Max.	Min.	Max.	Min.	Max.	
f _{MAX}		130	—	130	—	130	—	Mhz
t _{PLH} t _{PHL}	Propagation Delay CLK to xBx	1	6.2	—	5	1	4.3	ns
t _{PLH} t _{PHL}	Propagation Delay xBx to Ax	1	5.3	—	4.7	1.4	4	ns
t _{PLH} t _{PHL}	Propagation Delay LE to Ax	1	6	—	5.9	1.4	4.8	ns
t _{PLH} t _{PHL}	Propagation Delay SEL to Ax	1.1	6.4	—	6.2	1.3	5.2	ns
t _{PZH} t _{PZL}	Output Enable Time OEB to Ax or OEA to xBx	1	6	—	6.1	1	5.1	ns
t _{PHZ} t _{PLZ}	Output Disable Time OEB to Ax or OEA to xBx	1.4	5.4	—	4.6	1.7	4.2	ns
t _{SU}	Setup Time, Ax data before CLK↑	2.6		2.1		1.7		ns
t _{SU}	Setup Time, Bx data before LE	1.7		1.5		1.3		ns
t _{SU}	Setup Time, CLKEN before CLK↑	1.6		1.3		1		ns
t _H	Hold Time, Ax data after CLK↑	0.6		0.6		0.7		ns
t _H	Hold Time, Bx data after LE	0.9		0.9		1.1		ns
t _H	Hold Time, CLKEN after CLK↑	1		0.9		0.9		ns
t _w	Pulse Width, CLK HIGH or LOW	3.3		3.3		3.3		ns
t _w	Pulse Width, LExB LOW	3.3		3.3		3.3		ns
tsk(0)	Output Skew ⁽²⁾	—	—	—	—	—	500	ps

NOTES:

- See test circuits and waveforms. T_A = – 40°C to + 85°C.
- Skew between any two outputs of the same package and switching in the same direction.

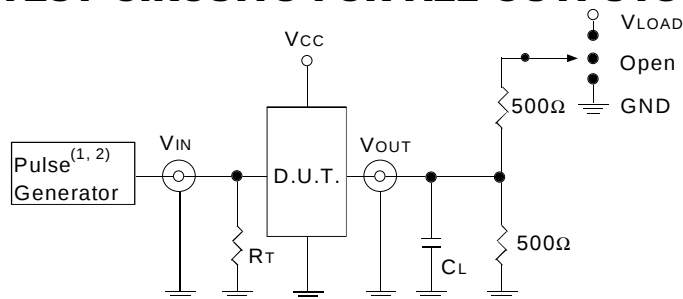
TEST CIRCUITS AND WAVEFORMS

TEST CONDITIONS

Symbol	V _{CC} (1)= 3.3V±0.3V	V _{CC} (1)= 2.7V	V _{CC} (2)= 2.5V±0.2V	Unit
V _{LOAD}	6	6	2 x V _{CC}	V
V _{IH}	2.7	2.7	V _{CC}	V
V _T	1.5	1.5	V _{CC} / 2	V
V _{LZ}	300	300	150	mV
V _{HZ}	300	300	150	mV
C _L	50	50	30	pF

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TEST CIRCUITS FOR ALL OUTPUTS



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DEFINITIONS:

C_L = Load capacitance: includes jig and probe capacitance.

R_T = Termination resistance: should be equal to Z_{OUT} of the Pulse Generator.

NOTES:

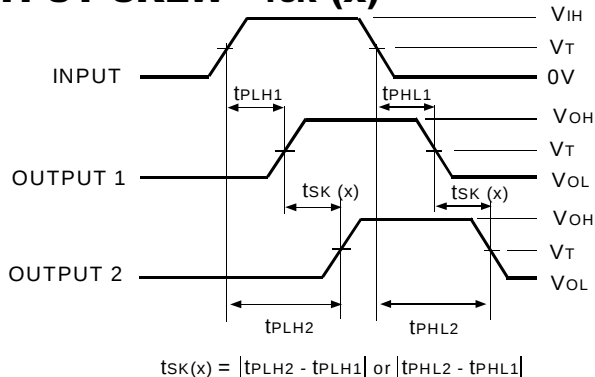
1. Pulse Generator for All Pulses: Rate ≤ 10MHz; t_F ≤ 2.5ns; t_R ≤ 2.5ns.
2. Pulse Generator for All Pulses: Rate ≤ 10MHz; t_F ≤ 2ns; t_R ≤ 2ns.

SWITCH POSITION

Test	Switch
Open Drain Disable Low Enable Low	V _{LOAD}
Disable High Enable High	GND
All Other tests	Open

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OUTPUT SKEW - t_{SK} (x)

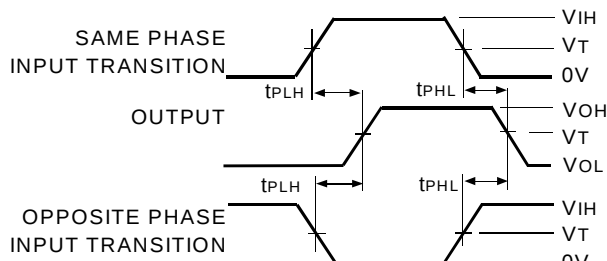


ALVC Link

NOTES:

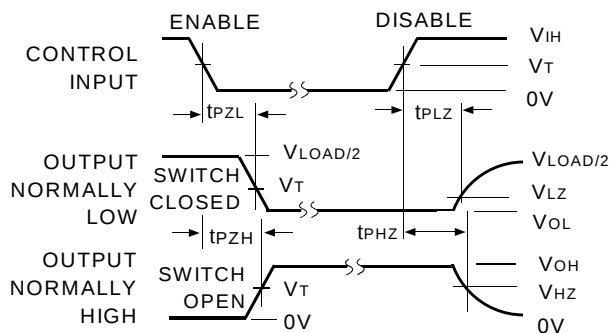
1. For t_{SK}(o) OUTPUT1 and OUTPUT2 are any two outputs.
2. For t_{SK}(b) OUTPUT1 and OUTPUT2 are in the same bank.

PROPAGATION DELAY



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ENABLE AND DISABLE TIMES

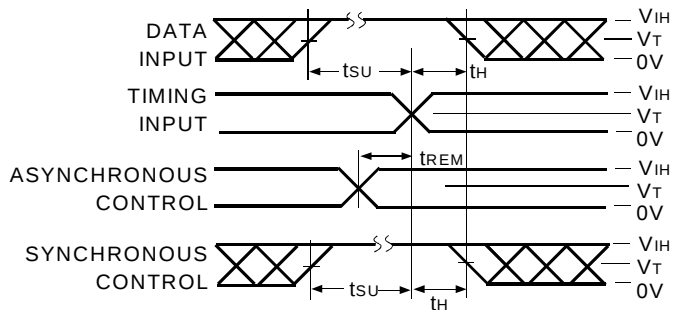


ALVC Link

NOTE:

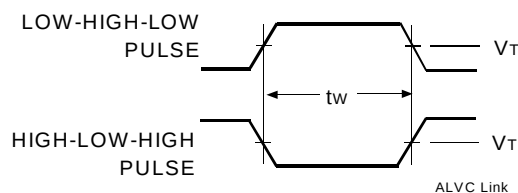
1. Diagram shown for input Control Enable-LOW and input Control Disable-HIGH.

SET-UP, HOLD, AND RELEASE TIMES



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PULSE WIDTH



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ORDERING INFORMATION

IDT	XX	ALVC	X	XX	XXX	XX	
Temp. Range	Bus-Hold	Family	Device Type	Package			
						PV	Shrink Small Outline Package (SO56-1)
						PA	Thin Shrink Small Outline Package (SO56-2)
						PF	Thin Very Small Outline Package (SO56-3)
					271		12-Bit To 24-Bit Multiplexed Bus Exchanger with 3-State Outputs
					16		Double-Density with Resistors, $\pm 24\text{mA}$
					H		Bus-Hold
					74		-40°C to $+85^{\circ}\text{C}$



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